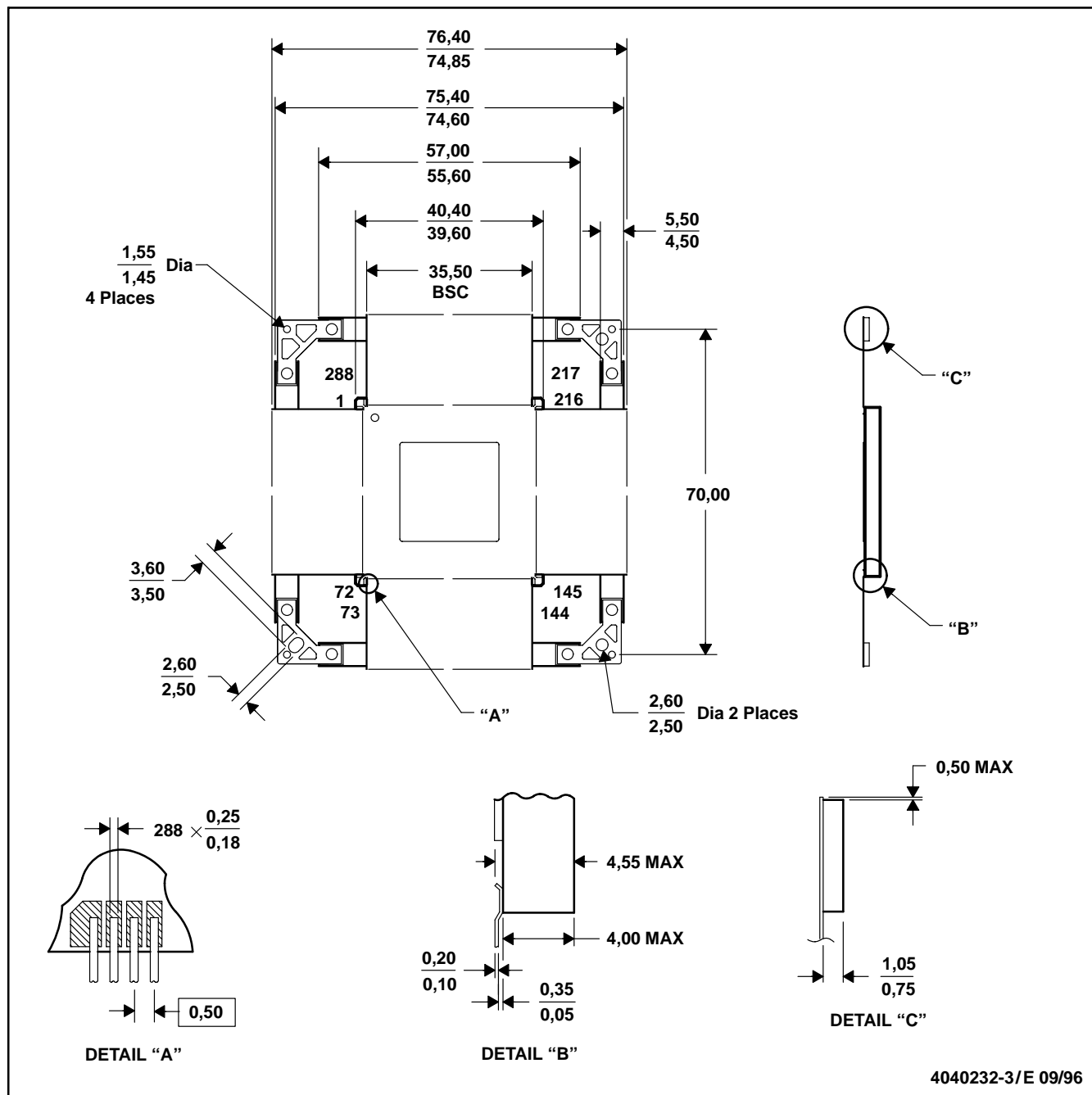


## HFH (R-CQFP-F288)

## CERAMIC QUAD FLATPACK WITH NCTB



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a metal lid.  
 D. The terminals are gold plated.  
 E. Falls within JEDEC MO-134 AC

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